

1. In the introduction section at line 51, author has described regarding insufficient bonding force between sensing layer and substrate in the past literature. But author has chosen 31.5°C, which is very low enough to do thermosetting. Has the author gone for substrate study with characterization and morphology at this temperature?
2. Under results and discussion at line 256, author has mentioned about bond between carbon-carbon atoms, that is broken due to plasma treatment at low temperature. Has the author done any experiment or proof to show this? Any bond energy released due to breakage? How could the author claim this or any literature behind this or reference link?
3. In figure 10, it has been shown regarding response of sensors at low temperature plasma treating that is at 31.5°C. How come this temperature is much enough to show good sensitivity and reliability in breaking carbon bonds?
4. In figure 15, has the author done any error analysis? Digital resistance can be claimed with good error data?
5. In section 3.3.1, tensile test setup, what is the tensile strain rate or displacement rate been used to do the test?
6. In the figure3, of interface for 3D motion control software, what is the step speed or increment rate been used for steeper motion? Please mention it in the article? Also mention the spray parameters used for fabrication?